



Product Summary (@T_A = +25°C)

V _{RRM} (V)	I ₀ (A)	V _F Max (V)	I _R Max (μA)
600	1	1.3	5

Description and Applications

The RS1JDF is a rectifier packaged in the low profile D-FLAT package. Providing fast recovery time for high efficiency, this device is ideal for use in general rectification applications such as:

- Switching Mode Power Supplies
- DC-DC Converters

1.0A SURFACE MOUNT FAST RECOVERY RECTIFIER

Features and Benefits

- Glass Passivated Die Construction
- Fast Recovery Time for High Efficiency
- Surge Overload Rating to 30A Peak
- High Current Capability
- Low Profile Design, Package Height Less than 1.1mm
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: D-FLAT
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Polarity: Cathode Band
- Weight: 0.035 grams (Approximate)

D-FLAT



Top View

Ordering Information (Note 4)

Part Number	Compliance	Case	Packaging
RS1JDF-13	AEC-Q101	D-FLAT	10,000/Tape & Reel

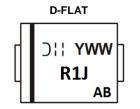
Notes:

EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



R1J= Product Type Marking Code)!! = Manufacturers' Code Marking YWW = Date Code Marking Y = Last Digit of Year (ex: 4 for 2014) WW = Week Code (01 to 53) AB = Foundry and Assembly Code



Unit

V

V A A

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load

Characteristic		Symbol	Value	1
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage (Note 5)		V _{RRM} V _{RWM} V _R	600	
RMS Reverse Voltage		V _{R(RMS)}	420	
Average Rectified Output Current	@T _A = +100°C	lo	1.0	
Non-Repetitive Peak Forward Surge Curre Single Half Sine-Wave Superimposed on F		I _{FSM}	30	

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Terminal (Note 9)	$R_{\theta JT}$	26	°C/W
Typical Thermal Resistance, Junction to Air (Note 9)	R _{0JA}	93	°C/W
Operating and Storage Temperature Range	$T_{J,} T_{STG}$	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 5)	V _{(BR)R}	600	_	_	V	$I_R = 10\mu A$
Forward Voltage	V _F		1.1 0.94	1.3 —	V	I _F = 1A, T _J = +25°C I _F = 1A, T _J = +125°C
Reverse Leakage Current (Note 5)	I _R		0.25 0.005	5	μA mA	V _R = 600V, T _J = +25°C V _R = 600V, T _J = +125°C
Reverse Recovery Time (Note 6)	t _{rr}	_		250	nS	$I_F = 0.5A, I_R = 1.0A, I_{RR} = 0.25A$
Total Capacitance (Note 7)	Ст	_	6	_	pf	$V_R = 4V_{DC}$, f = 1MHz

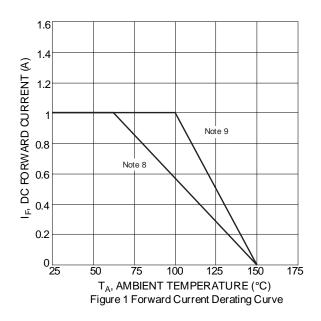
Notes: 5. Short duration pulse test used to minimize self-heating effect.

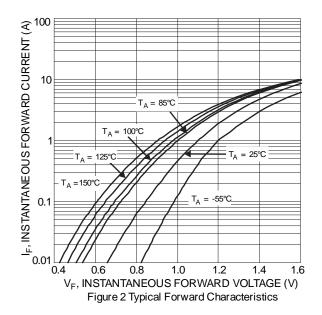
6. Measured with IF = 0.5A, IR = 1.0A, IRR = 0.25A. See Figure 7.

7. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

8. Device mounted on FR-4 substrate, 1"*1", 2oz, single-sided, PC boards with 0.1"*0.15" copper pads.

9. Device mounted on FR-4 substrate, 0.4"*0.5", 2oz, single-sided, PC boards with 0.2"*0.25" copper pads.





RS1JDF Document number: DS37258 Rev. 4 - 2 Downloaded from Arrow.com.



RS1JDF

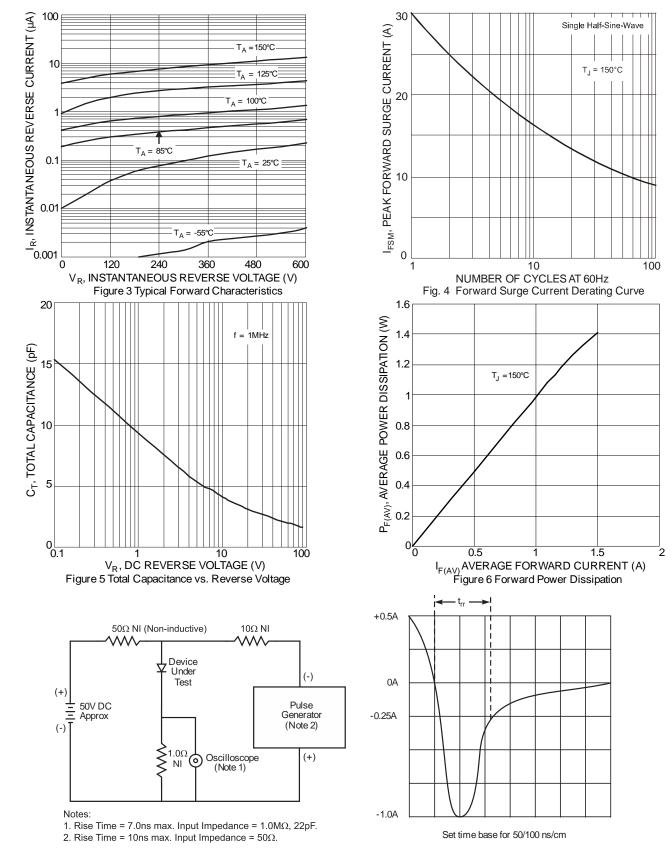


Figure 7 Reverse Recovery Time Characteristic and Test Circuit

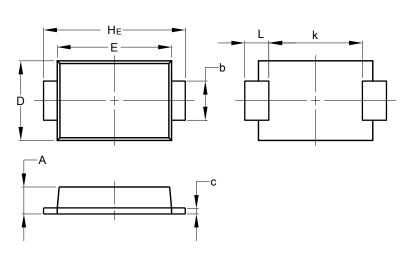


Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

D-FLAT

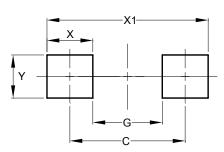
D-FLAT



D-FLAT					
Dim	Min	Max			
Α	0.90	1.10			
b	1.25	1.65			
С	0.10	0.40			
D	2.25	2.95			
Е	3.95	4.60			
k	2.80	-			
HE	5.00	5.60			
Ĺ	0.50	1.30			
All Dimensions in mm					

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)		
С	4.65		
G	2.80		
Х	1.85		
X1	6.50		
Y	1.70		

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